

Specification Sheet

High Purity, 50PPI/5mm**Stock No: NS6130-10-1011, CAS: 7440-50-8**

Product	:	Copper Metal Foam
Stock No	:	NS6130-10-1011
CAS	:	7440-50-8
Purity	:	≥99.8%
Porosity	:	≥70%
Dimension	:	500mm X 500mm
Thickness	:	5mm
PPI	:	50
Molecular Formula	:	Cu
Molecular weight	:	63.55g/mol
Density	:	8.96g/cm ³
Bulk Density	:	0.80-0.85 g/cc
Melting point	:	1085°C
Boiling point	:	2562°C
Thermal expansion	:	16.5μm.m-1.k-1
Thermal conductivity	:	401W.m-1.k-1
Tensile strength	:	1.25N/mm
Young's modulus	:	110-128GPa
Shear strength	:	190Psi
Vickers hardness	:	369MPa
Poisson's ratio	:	0.34
Electrical resistivity	:	1.673μΩ-cm
Specific heat	:	0.39kj/kgK
Electronegativity	:	1.90paulings
Heat of fusion	:	13.26kJ.mol-1

Intelligent Materials Pvt. Ltd.

www.nanoshel.com, sales@nanoshel.com

Heat of vaporization : 300.4kJ.mol⁻¹

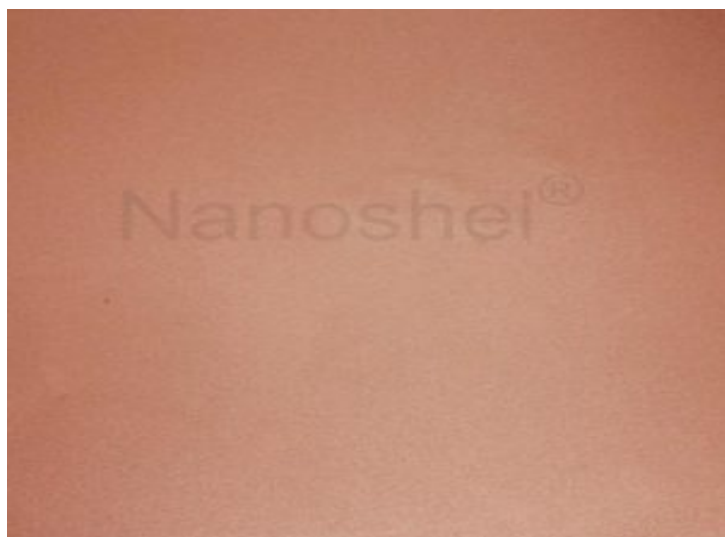
Main Inspect Verifier : Manager QC



Note: Product Specification are subject to amendment and may change over time



Characterization of High Purity, 50PPI/5mm



Copper Metal Foam



NANOSHEL
Creating Miracles in Black